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DATE: October 7, 2020

PCN #: 2487

PCN Title: Fab Porting from Global Foundries to MagnaChip, Assembly Site Transfer, and Datasheet Change

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



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**PRODUCT CHANGE NOTICE****PCN-2487 REV 1**

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Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
October 7, 2020	January 7, 2021	Analog	Fab, A/T Site, and Datasheet	<b>2487</b>
<b>TITLE</b>				
Fab Porting from Global Foundries to Magnachip, Assembly & Test Site Transfer, and Datasheet Change				
<b>DESCRIPTION OF CHANGE</b>				
<p>As already announced in PCN-2325 Global Foundries in Woodlands, Singapore closed their 0.35um technology wafer production on December 15, 2018.</p> <p>In order to assure continuity of supply, Diodes transferred wafer manufacturing to Magnachip Semiconductor located in Heungdeok-gu, Korea using 0.18um technology.</p> <p>This PCN is being issued to notify customers that, in order to assure continuity of supply, Diodes will also transfer assembly and test to Greatek Electronics Inc. in Miaoli, Taiwan. Diodes is also changing the device marking including Diodes logo (see Figure 1). For select products, the device datasheet will be changed. See Tables 2 and 3, and Figures 2 and 3.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers. Refer to the attached qualification / reliability report (embedded in this file).</p>				
<b>IMPACT</b>				
Continuity of Supply. No impact to fit.				
<b>PRODUCTS AFFECTED</b>				
Table 1 - Fab Porting (Global Foundry to Magnachip) and New A/T Site (Greatek) Table 2 - Fab Porting (Global Foundry to Magnachip) and Updated Datasheet (IDD) Table 3 - Fab Porting (Global Foundry to Magnachip), New A/T Site (Greatek) and Updated Datasheet (IDD)				
<b>WEB LINKS</b>				
<b>Manufacturer's Notice:</b>	<a href="https://www.diodes.com/quality/product-change-notice/diodes-product-change-notice/">https://www.diodes.com/quality/product-change-notice/diodes-product-change-notice/</a>			
<b>For More Information Contact:</b>	<a href="http://www.diodes.com/contacts.html">http://www.diodes.com/contacts.html</a>			
<b>Data Sheet:</b>	<a href="http://www.diodes.com/catalog">http://www.diodes.com/catalog</a>			
<b>DISCLAIMER</b>				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Fab Porting (Global Foundry to Magnachip) and New A/T Site (Gretek)			
PI6C20400BHEX	PI6C557-03ALEX		

Table 2 - Fab Porting (Global Foundry to Magnachip) and Updated Datasheet (IDD) (see Figure 2 and Figure 3 for datasheet update)			
PI6C557-03LEX	PI6C557-05BLE	PI6C557-05BLEX	

Table 3 - Fab Porting (Global Foundry to Magnachip), New A/T Site (Gretek) and Updated Datasheet (IDD) (see Figure 3 for datasheet update)			
PI6C557-05LEX			

Figure 1. Marking Change



Old marking	New marking
 <p>YY: Year WW: Work Week 1st X: Assembly Code 2nd X: Fab Code Bar above fab code means Cu wire</p>	 <p>Y: Die Rev YY: Year WW: Work Week 1st X: Assembly Code 2nd X: Fab Code Bar above fab code means Cu wire</p>

Figure 2: PI6C557-03LEX IDD Datasheet Update

Before

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>DD</sub>	Operating Supply Current	R <sub>L</sub> = 50Ω, C <sub>L</sub> = 2pF			65	mA
I <sub>DDOE</sub>		OE = LOW			35	mA

After

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>DD</sub>	Operating Supply Current	R <sub>L</sub> = 50Ω, C <sub>L</sub> = 2pF			<b>95</b>	mA
I <sub>DDOE</sub>		OE = LOW			<b>50</b>	mA

Figure 3: PI6C557-05BLE, PI6C557-05BLEX and PI6C557-05LEX IDD Update

Before

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>DD</sub>	Operating Supply Current	R <sub>L</sub> = 50Ω, C <sub>L</sub> = 2pF @100MHz		105	120	mA
I <sub>DDOE</sub>		OE = LOW		40	50	mA

After

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>DD</sub>	Operating Supply Current	R <sub>L</sub> = 50Ω, C <sub>L</sub> = 2pF @100MHz		105	<b>130</b>	mA
I <sub>DDOE</sub>		OE = LOW		40	50	mA